



$V_{RRM} = 50\text{ V} - 1000\text{ V}$   
 $I_F = 2\text{ A}$

### Features

- Types up to 1000 V  $V_{RRM}$
- Ideal for printed circuit board
- Surge overload rating to 65 Amps peak
- High temperature soldering guaranteed 250°C/10 seconds
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Reliable, low cost construction utilizing molded plastic technique

KBPM Package



### Mechanical Data

Leads: Tin plated copper

Weight: 0.047 oz, 1.33 g

Mounting position: Any

Terminals: Leads solderable per MIL-STD-202, Method 208

Polarity: Polarity marked on body

### Maximum ratings, at $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	KBPM206G	KBPM206G	KBPM210G	Unit
Repetitive peak reverse voltage	$V_{RRM}$		600	800	1000	V
RMS reverse voltage	$V_{RMS}$		420	560	700	V
DC blocking voltage	$V_{DC}$		600	800	1000	V
Continuous forward current	$I_F$	$T_C \leq 65\text{ }^\circ\text{C}$	2	2	2	A
Surge non-repetitive forward current, Half Sine Wave	$I_{FSM}$	$T_C = 25\text{ }^\circ\text{C}$ , $t_p = 8.3\text{ ms}$	65	65	65	A
Operating temperature	$T_J$	-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$

### Electrical characteristics, at $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	KBPM206G	KBPM206G	KBPM210G	Unit
Diode forward voltage	$V_F$	$I_F = 2\text{ A}$ , $T_J = 25\text{ }^\circ\text{C}$	1.1	1.1	1.1	V
Reverse current	$I_R$	$V_R = 50\text{ V}$ , $T_J = 25\text{ }^\circ\text{C}$	5	5	5	$\mu\text{A}$
		$V_R = 50\text{ V}$ , $T_J = 125\text{ }^\circ\text{C}$	500	500	500	

### Thermal characteristics

Thermal resistance, junction - case	$R_{\theta JC}$	14.0	14.0	14.0	14.0	$^\circ\text{C/W}$
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